

Cryomodule Development & Integration Experience: Essential factors for improving reliability in cryomodule assembly

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Presenter: TRUBLET, thierry (CEA Saclay)

Session Classification: WG 3 : Cryomodule - Conveners: E. Harms (FNAL), H. Nakai (KEK), J. Preble (Jlab), S. Berry (CEA) (30 minutes Coffee Break incl.)